

Panel Discussion Update: Life Cycles of Sockets

Jason Mroczkowski (Cohu)
James Tong (Texas Instruments)



Panel Members

Jason Mroczkowski (Cohu)

James Tong (Texas Instruments)

James Migliaccio (Qorvo)

Rahima Mohammed (Intel)

Valts Treibergs (Cohu)

Yoinjun Shi (TwinSolution)

Jiachun (Frank) Zhou (Smiths Interconnect)



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Mission

Alignment of expectation between User and suppliers

Socket manufacturer:

Focused on mechanical life of contact

- Interface Wear
- Force
- Cres variation
- Cleaning intervals
- Room temp
- Temp ramp
- CCC
- RF/High speed data

Socket user:

Focused on production yield

- First pass yield
- METS test
- Temp cycling
- Power cycling
- Disconnect between contact and whole socket performance
- Contamination
- Contact Performance Maintenance System
- Use of actual devices vs. surrogates



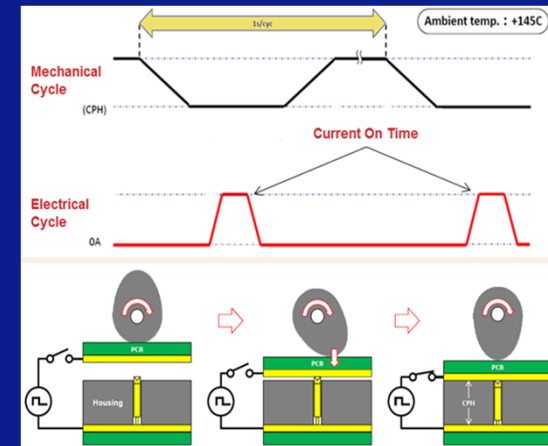
TestConX Presentation Guide & Template 1.0 (Replace with your title using Insert | Header and Footer menu)

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Update

- Too much to standardize in one attempt
- Started with limited scope:
 - Life Cycle testing with critical variables defined
 - Electrical, mechanical and thermal stress
- Proposed:
 - Adopt METS Test Procedure
 - Pending duty cycle, contact material, number of pins samples, test current and temperature



Next Step

- Setup a open forum for more participation to spec
 - Duty cycle (10%?)
 - contact material (SAC?, NiPdAu?)
 - # pin samples (10 or more?)
 - Current (5A/pin?)
 - Temperature (Pin spec value?)
- Continue the panel team meetings



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